FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 16665A

Generic Copy

Issue Date: 30-Jul-2012

TITLE: Discontinuance of Part number 12095-801-XTD and conversion to 12095-804-XTD

PROPOSED FIRST SHIP DATE: 30-Oct-2012

AFFECTED CHANGE CATEGORY(S): Assembly – Plating Material

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Sarah Sanico<ffxxxh@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This is to inform customer that we will no longer supply the 12095-801-XTD (SnPb leadfinish) and these will be converted to 12095-804-XTD (Matte tin).

The reason for change was due to ASE Kaohsiung had phased out their internal SnPb plating process for ASE GP (Green Product) policy.

Please refer to table below for the bill of material:

Package	BOM	Current	Proposed
LQFP	Epoxy	ABL-8360/2288A	2288A
	Mold Compound	EME-7320A/ CEL9200THF	CEL9200THF
	Lead Finish	SnPb	Matte Tin

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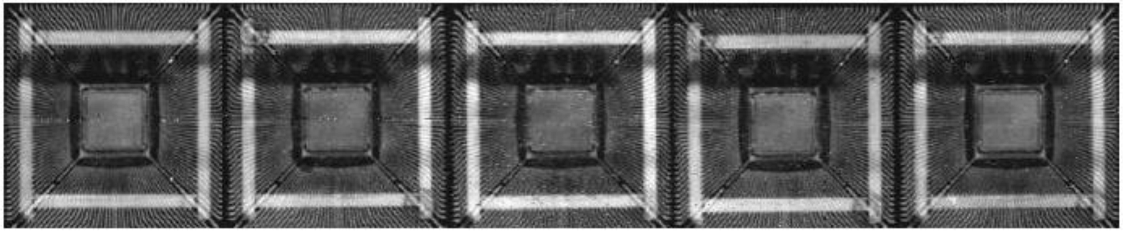
QUALIFICATION DATA:

The assembly qualification tests have concluded with passing results. No failures were incurred on all tests. On Semiconductor released the package and green material set under consideration for dry pack level 3 of IPC/JEDEC standard J-STD-020 (Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices).

Test	Conditions	Result
Autoclave	121 degC/100% RH	Passed
Ball Shear test	N/A	Passed
Bond Pull test	N/A	Passed
External Visual	N/A	Passed
Flammability	N/A	Passed
High Temperature Bake	175 degC	Passed
Mark permanency	N/A	Passed
Moisture Preconditioning • Bake • Humidity Soak • Reflow	125 degC 85 degC/60% RH 260 degC	Passed
Physical Dimension	N/A	Passed
Preconditioning Temperature Cycling	-65 degC/ 150 degC	Passed
Scanning Acoustic Microscopy	N/A	Passed
Solderability	245 degC	Passed
Temperature Cycling	-65 degC/ 150 degC	Passed
X-ray	N/A	Passed

Table 1: SCANNING ACOUSTIC MISCROPY PHOTO

PRIOR MOISTURE PRECONDITIONING,



AFTER MOISTURE PRECONDITIONING,

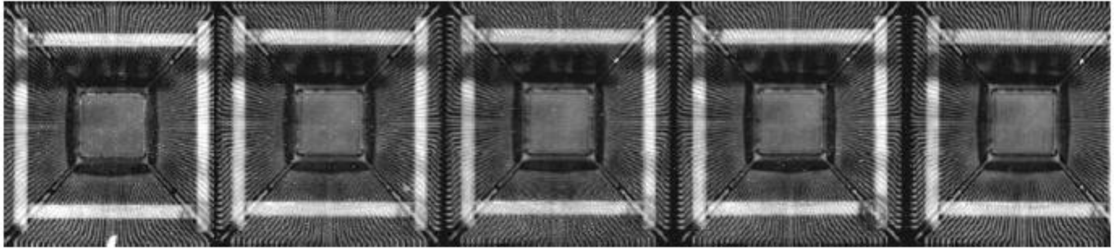


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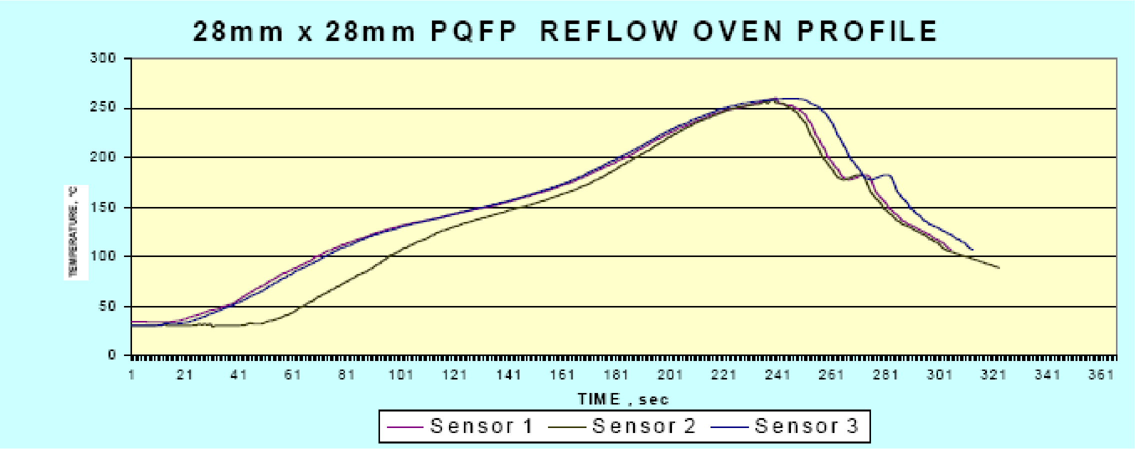
Table 2: REFLOW OVEN PROFILE



CHANGED PART IDENTIFICATION:

Change from 12095-801-XTD to 12095-804-XTD

List of affected Customer Specific Parts:

12095-801-XTD